

Electronic Patent Application Fee Transmittal

Application Number:	10581395
Filing Date:	14-Aug-2008
Title of Invention:	Chip Scale Package and Method of Assembling the Same
First Named Inventor/Applicant Name:	Hien Boon Tan
Filer:	Carl Joseph Pellegrini/ruth swanson
Attorney Docket Number:	Q78657

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Notice of appeal	1401	1	620	620
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$130 paid	1253	1	1140	1140
Miscellaneous:				
Total in USD (\$)				1760